MSP430F2132 Device Erratasheet

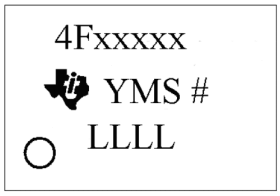
1 Revision History

✓ The check mark indicates that the issue is present in the specified revision.

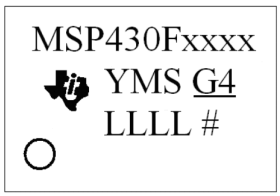
Errata Number	Rev C	Rev B	Rev A
BCL12	✓	✓	✓
BCL13			✓
BCL16	✓	✓	✓
CPU19	✓	✓	✓
EEM20	✓	✓	✓
FLASH19	✓	✓	✓
FLASH24	✓	✓	✓
FLASH27	✓	✓	✓
FLASH36	✓	✓	✓
PORT12	✓	✓	✓
SYS15	✓	✓	✓
TA12	✓	✓	✓
TA16	✓	✓	✓
TA21	✓	✓	✓
TAB22	✓	✓	✓
USCI20	✓	✓	✓
USCI21	✓	✓	✓
USCI22	✓	✓	✓
USCI23	✓	✓	✓
USCI24	✓	✓	✓
USCI25	✓	✓	✓
USCI26	✓	✓	✓
USCI28	✓	✓	✓
USCI30	✓	✓	✓
USCI35	✓	✓	✓
XOSC5	✓	✓	✓
XOSC8		✓	✓

2 Package Markings

PW28 *TSSOP (PW), 28 Pin*



YM = Year and Month Date Code
LLLL = LOT Trace Code
S = Assembly Site Code
# = DIE Revision
o = PIN 1



YM = Year and Month Date Code
LLLL = LOT Trace Code
S = Assembly Site Code
# = DIE Revision
o = PIN 1

RHB32 *QFN (RHB), 32 Pin*

YM = Year and Month Date Code
LLLL = LOT Trace Code
S = Assembly Site Code
# = DIE Revision
o = PIN 1

3 Detailed Bug Description

BCL12 *BCS Module*

Function Switching RSELx or modifying DCOCTL can cause DCO dead time or a complete DCO stop

Description After switching RSELx bits (located in register BCSCTL1) from a value of >13 to a value of <12 OR from a value of <12 to a value of >13, the resulting clock delivered by the DCO can stop before the new clock frequency is applied. This dead time is approximately 20 us. In some instances, the DCO may completely stop, requiring a power cycle.

Furthermore, if all of the RSELx bits in the BSCTL1 register are set, modifying the DCOCTL register to change the DCOx or the MODx bits could also result in DCO dead time or DCO hang up.

Workaround - When switching RSEL from >13 to <12, use an intermediate frequency step. The intermediate RSEL value should be 13.

Current RSEL	Target RSEL	Recommended Transition Sequence
15	14	Switch directly to target RSEL
14 or 15	13	Switch directly to target RSEL
14 or 15	0 to 12	Switch to 13 first, and then to target RSEL (two step sequence)
0 to 13	0 to 12	Switch directly to target RSEL

AND

- When switching RSEL from <12 to >13 it's recommended to set RSEL to its default value first (RSEL = 7) before switching to the desired target frequency.

AND

- In case RSEL is at 15 (highest setting) it's recommended to set RSEL to its default value first (RSEL = 7) before accessing DCOCTL to modify the DCOx and MODx bits. After the DCOCTL register modification the RSEL bits can be manipulated in an additional step.

In the majority of cases switching directly to intermediate RSEL steps as described above will prevent the occurrence of BCL12. However, a more reliable method can be implemented by changing the RSEL bits step by step in order to guarantee safe function without any dead time of the DCO.

Note that the 3-step clock startup sequence consisting of clearing DCOCTL, loading the BCSCTL1 target value, and finally loading the DCOCTL target value as suggested in the in the "TLV Structure" chapter of the MSP430x2xx Family User's Guide is not affected by BCL12 if (and only if) it is executed after a device reset (PUC) prior to any other modifications being made to BCSCTL1 since in this case RSEL still is at its default value of 7. However any further changes to the DCOx and MODx bits will require the consideration of the workaround outlined above.

BCL13 *BCS Module*

Function DCO powerup halt

Description When subject to very slow Vcc rise times, the device may enter into a state where the DCO does not oscillate. No JTAG access or program execution is possible and the device will remain in a reset state until the supply voltage is disconnected.

Workaround Apply a Vcc poweron ramp >= 10V/second under all power-on/power-cycle scenarios.

BCL16 *BCS Module*

Function SMCLK clock source selection from XT1/VLO to DCO

Description When the MCLK and the SMCLK do not use the DCO, the DCO is off. The DCO does not start if the clock source for SMCLK is changed from XT1/VLO to DCO. As a result, the SMCLK remains high. Note: This is only true for SMCLK. The DCO starts if the clock source of MCLK is set to DCO.

Workaround Set clock source of MCLK to DCO by either:

1)setting the selection bits SELMx of BCSCTL2 register to '00' or '01'.

OR

2)setting the OFIFG bit of IFG1 register. Note: This triggers the oscillator fault logic that automatically starts the DCO. Reset the OFIFG bit to further use the XT1/VLO.

For both options, if the XT1/VLO is still required to source MCLK, revert the clock source of MCLK back to XT1/VLO afterwards.

CPU19 *CPU Module*

Function CPUOFF modification may result in unintentional register read

Description If an instruction that modifies the CPUOFF bit in the Status Register is followed by an instruction with an indirect addressed operand (e.g. MOV @R8, R9, RET, POP, POPM), an unintentional register read operation can occur during the wakeup of the CPU. If the unintentional read occurs to a read sensitive register (e.g. UCB0RXBUF, TAIV), which changes its value or the value of other registers (IFG's), the bug leads to lost interrupts or wrong register read values.

Workaround Insert a NOP instruction after each CPUOFF instruction.

EEM20 *EEM Module*

Function Debugger might clear interrupt flags

Description During debugging read-sensitive interrupt flags might be cleared as soon as the debugger stops. This is valid in both single-stepping and free run modes.

Workaround None.

FLASH19 *FLASH Module*

Function EEI feature does not work for code execution from RAM

Description When the program is executed from RAM, the flash controller EEI feature does not work. The erase cycle is suspended and the interrupt is serviced, but there is a problem while resuming with the erase cycle.

Addresses applied to flash are different than the actual values while resuming erase cycle after ISR execution.

Workaround None

FLASH24 *FLASH Module*

Function Write or erase emergency exit can cause failures

Description When a flash write or erase is abruptly terminated, the following flash accesses by the CPU may be unreliable resulting in erroneous code execution. The abrupt termination can be the result of one the following events:

1) The flash controller clock is configured to be sourced by an external crystal. An oscillator fault occurs thus stopping this clock abruptly.

or

2) The Emergency Exit bit (EMEX in FCTL3) when set forces a write or an erase operation to be terminated before normal completion.

or

3) The Enable Emergency Interrupt Exit bit (EEIEX in FCTL1) when set with GIE=1 can lead to an interrupt causing an emergency exit during a Flash operation.

Workaround 1) Use the internal DCO as the flash controller clock provided from MCLK or SMCLK.

or

2) After setting EMEX = 1, wait for a sufficient amount of time before Flash is accessed again.

or

3) No Workaround. Do not use EEIEX bit.

FLASH27 *FLASH Module*

Function EEI feature can disrupt segment erase

Description When a flash segment erase operation is active with EEI feature selected (EEI=1 in FLCTL1) and GIE=0, the following can occur:

An interrupt event causes the flash erase to be stopped, and the flash controller expects an RETI to resume the erase. Because GIE=0, interrupts are not serviced and RETI will never happen.

Workaround 1) Do not set bit EEI=1 when GIE = 0.

or,

2) Force an RETI instruction during the erase operation during the check for BUSY=1 (FCLTL3).

Sample code:

```
MOV R5, 0(R5) ; Dummy write, erase segment
LOOP: BIT #BUSY, &FCTL3 ; test busy bit
JMP SUB_RETI ; Force RETI instruction
JNZ LOOP ; loop while BUSY=1
SUB_RETI: PUSH SR
RETI
```

FLASH36 *FLASH Module*

Function Flash content may degrade due to aborted page erases

Description If a page erase is aborted by EEIEX, the flash page containing the last instruction before erase operation will start to degrade. This effect is incremental and, after repetitions, may lead to corrupted flash content.

Workaround - Use the EEI (interrupted erasing) feature instead of EEIEX (abort erasing).

or

- A PSA checksum can be calculated over affected flash page using the marginal read mode (marginal 0). If PSA sum differs from expected PSA value the affected flash page has to be reprogrammed.

or

- Start flash erasing from RAM and limit system frequency to <1MHz (to ensure 6-us delay after EEIEX). If the last instruction before erasing is located in RAM, flash cell degradation does not occur.

PORT12 *PORT Module*

Function PxIFG is set on PUC

Description The PxIN register is cleared when a PUC is asserted, and it regains the original value after the PUC is de-asserted. If the PxIN register bits read high, asserting a PUC causes clearing of the register, which results in a high-to-low transition. Once the PUC is de-asserted, the PxIN register is restored to high, which results in a low-to-high transition. This behavior results in the PxIFG being set regardless of the PxIES setting.

Workaround Prior to setting PxIE bits ensure that corresponding PxIFG bits are cleared.

SYS15 *SYS Module*

Function LPM3 and LPM4 currents exceed specified limits

Description LPM3 and LPM4 currents may exceed specified limits if the SMCLK source is switched from DCO to VLO or LFXT1 just before the instruction to enter LPM3 or LPM4 mode.

Workaround After clock switching, a delay of at least four new clock cycles (VLO or LFXT1) must be implemented to complete the clock synchronization before going into LPM3 or LPM4.

TA12 *TIMER_A Module*

Function Interrupt is lost (slow ACLK)

Description Timer_A counter is running with slow clock (external TACLK or ACLK)compared to MCLK. The compare mode is selected for the capture/compare channel and the CCRx register is incremented by one with the occurring compare interrupt (if TAR = CCRx). Due to the fast MCLK the CCRx register increment (CCRx = CCRx+1) happens before the Timer_A counter has incremented again. Therefore the next compare interrupt should happen at once with the next Timer_A counter increment (if TAR = CCRx + 1). This interrupt gets lost.

Workaround Switch capture/compare mode to capture mode before the CCRx register increment. Switch back to compare mode afterwards.

TA16 *TIMER_A Module*

Function First increment of TAR erroneous when IDx > 00

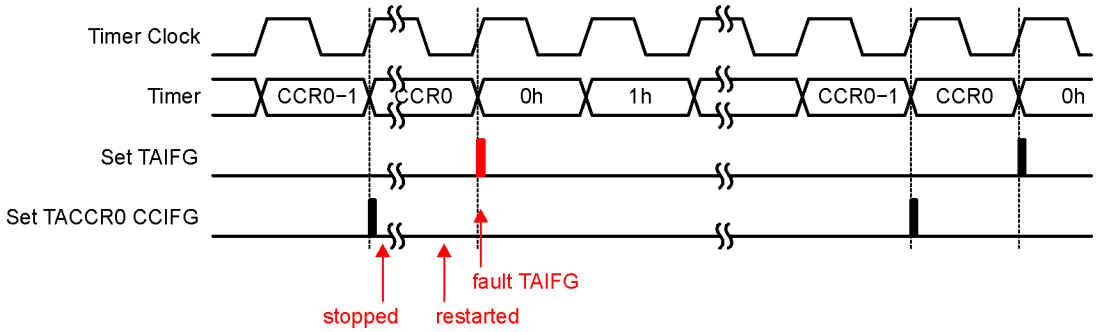
Description The first increment of TAR after any timer clear event (POR/TACLR) happens immediately following the first positive edge of the selected clock source (INCLK, SMCLK, ACLK or TACLK). This is independent of the clock input divider settings (ID0, ID1). All following TAR increments are performed correctly with the selected IDx settings.

Workaround None

TA21 *TIMER_A Module*

Function TAIFG Flag is erroneously set after Timer A restarts in Up Mode

Description In Up Mode, the TAIFG flag should only be set when the timer resets from TACCR0 to zero. However, if the Timer A is stopped at TAR = TACCR0, then cleared (TAR=0) by setting the TACLR bit, and finally restarted in Up Mode, the next rising edge of the TACLK will erroneously set the TAIFG flag.



Workaround None.

TAB22 *TIMER_A/TIMER_B Module*

Function Timer_A/Timer_B register modification after Watchdog Timer PUC

Description Unwanted modification of the Timer_A/Timer_B registers TACTL/TBCTL and TAIV/TBIV can occur when a PUC is generated by the Watchdog Timer(WDT) in Watchdog mode and any Timer_A/Timer_B counter register TACCRx/TBCCRx is incremented/decremented (Timer_A/Timer_B does not need to be running).

Workaround Initialize TACTL/TBCTL register after the reset occurs using a MOV instruction (BIS/BIC may not fully initialize the register). TAIV/TBIV is automatically cleared following this initialization.

Example code:

MOV.W #VAL, &TACTL

or

MOV.W #VAL, &TBCTL

Where, VAL=0, if Timer is not used in application otherwise, user defined per desired function.

USCI20 *USCI Module*

Function I2C Mode Multi-master transmitter issue

Description When configured for I2C master-transmitter mode, and used in a multi-master environment, the USCI module can cause unpredictable bus behavior if all of the following four conditions are true:

1 - Two masters are generating SCL

And

2 - The slave is stretching the SCL low phase of an ACK period while outputting NACK on SDA

And

3 - The slave drives ACK on SDA after the USCI has already released SCL, and then the SCL bus line gets released

And

4 - The transmit buffer has not been loaded before the other master continues communication by driving SCL low

The USCI will remain in the SCL high phase until the transmit buffer is written. After the transmit buffer has been written, the USCI will interfere with the current bus activity and may cause unpredictable bus behavior.

Workaround 1 - Ensure that slave doesn't stretch the SCL low phase of an ACK period

Or

2 - Ensure that the transmit buffer is loaded in time

Or

3 - Do not use the multi-master transmitter mode

USCI21 *USCI Module*

Function UART IrDA receive filter

Description The IrDA receive filter can be used to filter pulses with length UCAIRRXFL configured in UCAxIRRCTL register. If UCIRRXFE is set the IrDA receive decoder may filter out pulses longer than the configured filter length depending on frequency of BRCLK. This is resulting in framing errors or corrupted data on the receiver side.

Workaround Depending on the used baud rate and the configured filter length a maximum frequency for BRCLK needs to be set to avoid this issue:

For baud rates equal and higher than 115.000 the maximum allowed BRCLK frequency is equal to the max specified system frequency.

$$\text{Max BRCLK} = \frac{\text{Filter Length} + 64}{2} \times \frac{\text{Baud Rate} \times 16}{3 \times 10^6}$$

Baud Rate	Filter Length UCIRRXFL (dec)	Max BRCLK (MHz)
9600	64	3.28
	32	2.46
	16	2.05
	8	1.84
	4	1.74
	2	1.69
	1	1.66
	0	1.64
19200	64	6.55
	32	4.92
	16	4.1
	8	3.69
	4	3.48
	2	3.38
	1	3.33
	0	3.28
38400	64	13.11
	32	9.83
	16	8.19
	8	7.37
	4	6.96
	2	6.76
	1	6.66
	0	6.55
56000	64	19.11
	32	14.34
	16	11.95
	8	10.75
	4	10.15
	2	9.86
	1	9.71
	0	9.56

USCI22 *USCI Module*

Function I2C Master Receiver with 10-bit slave addressing

Description Unexpected behavior of the USCI_B can occur when configured in I2C master receive mode with 10-bit slave addressing under the following conditions:

1) The USCI sends first byte of slave address, the slave sends an ACK and when second address byte is sent, the slave sends a NACK.

2) Master sends a repeat start condition (If UCTXSTT=1).

3) The first address byte following the repeated start is acknowledged.

However, the second address byte is not sent, instead the Master incorrectly starts to receive data and sets UCBxRXIFG=1.

Workaround Do not use repeated start condition instead set the stop condition UCTXSTP=1 in the NACK ISR prior to the following start condition (USTXSTT=1).

USCI23 *USCI Module*

Function UART transmit mode with automatic baud rate detection

Description Erroneous behavior of the USCI_A can occur when configured in UART transmit mode with automatic baud rate detection. During transmission if a "Transmit break" is initiated (UCTXBRK=1), the USCI_A will not deliver a stop bit of logic high, instead, it will send a logic low during the subsequent synch period.

Workaround 1) Follow User's Guide instructions for transmitting a break/synch field following UCSWRST=1.

Or,

2) Set UCTXBRK=1 before an active transmission, i.e. check for bit UCBUSY=0 and then set UCTXBRK=1.

USCI24 *USCI Module*

Function Incorrect baud rate information during UART automatic baud rate detection mode

Description Erroneous behavior of the USCI_A can occur when configured in UART mode with automatic baud rate detection. After automatic baud rate measurement is complete, the UART updates UCAxBR0 and UCAxBR1. Under Oversampling mode (UCOS16=1), for baud rates that should result in UCAxBRx=0x0002, the UART incorrectly reports it as UCAxBRx=0x5555.

Workaround When break/synch is detected following the automatic baud rate detection, the flag UCBRK flag is set to 1. Check if UCAxBRx=0x5555 and correct it to 0x0002.

USCI25 *USCI Module*

Function TXIFG is not reset when NACK is received in I2C mode

Description When the USCI_B module is configured as an I2C master transmitter the TXIFG is not reset after a NACK is received if the master is configured to send a restart (UCTXSTT=1 & UCTXSTP=0).

Workaround Reset TXIFG in software within the NACKIFG interrupt service routine

USCI26 *USCI Module*

Function Tbuf parameter violation in I2C multi-master mode

Description In multi-master I2C systems the timing parameter Tbuf (bus free time between a stop condition and the following start) is not guaranteed to match the I2C specification of 4.7us in standard mode and 1.3us in fast mode. If the UCTXSTT bit is set during a running I2C transaction, the USCI module waits and issues the start condition on bus release causing the violation to occur.

Note: It is recommended to check if UCBBUSY bit is cleared before setting UCTXSTT=1.

Workaround None

USCI28 *USCI Module*

Function Timing of USCI I2C interrupts may cause device reset due to automatic clear of an IFG.

Description When certain USCI I2C interrupt flags (IFG) are set and an automatic flag-clearing event on the I2C bus occurs, it results in an errant ISR call to the reset vector. This will only happen when the IFG is cleared within a critical time window (~6 CPU clock cycles) after a USCI interrupt request occurs and before the interrupt servicing is initiated. The affected interrupts are UCBxTXIFG, UCSTPIFG, UCSTTIFG and UCNACKIFG.

The automatic flag-clearing scenarios are described in the following situations:

(1) A pending UCBxTXIFG interrupt request is cleared on the falling SCL clock edge following a NACK.

(2) A pending UCSTPIFG, UCSTTIFG, or UCNACKIFG interrupt request is cleared by a following Start condition.

Workaround (1) Polling the affected flags instead of enabling the interrupts.

or

(2) Ensuring the above mentioned flag-clearing events occur after a time delay of 6 CPU clock cycles has elapsed since the interrupt request occurred and was accepted.

or

(3) At program start, check any applicable enabled IE bits such as UCBxTXIE, UCBxRXIE, UCSTTIE, UCSTPIE or UCNACKIE for a reset (A PUC will clear all of the IE bits of interest). If no PUC occurred then the device ran into the above mentioned errant condition and the program counter will need to be restored using an RETI instruction.

; ------- Workaround (3) example for TXIFG ------------

Note: For assembly code use code snippet shown below and insert prior to user code

main

bit.b #UCBxTXIE ,&IE2 ; if TXIE is set, errant call occurred

jz start_normal ; if not start main program

reti ; else return from interrupt call

start_normal

... ; Application code continues

Note: For C code the workaround will need to be executed prior to the CSTARTUP routine. The steps for modifying the CSTARTUP routine are IDE dependent.

Examples for Code Composer and IAR Embedded Workbench are shown below.

IAR Embedded Workbench:

1) The file cstartup.s43 is found at: ...\IAR Systems\<Current Embedded Workbench Version>\430\src\lib\430

2) Create a local copy of this file and link it to the project. Do not rename the file.

3) In the copy insert the following code prior to stack pointer initialization as shown:

```
#define IE2 (0x0001)
BIT.B #0x08,&IE2 ; if TXIE is set, errant call occurred
JZ Start_Normal ; if not start main program
RETI ; else return from interrupt call
// Initialize SP to point to the top of the stack.
Start_Normal
MOV #SFE(CSTACK), SP
// Ensure that main is called.
```

Code Composer:

1) The file boot.c is found at ...\Texas Instruments\<Current Code Composer Version>\tools\compiler\MSP430\lib\rtssrc.zip

2) Extract the file from rtssrc.zip and create a local copy. Link the copy to the project. Do not rename this file.

3) In the copy insert the following code prior to stack pointer initialization as shown:

```
__asm("\t BIT.B\t #0x08,&0x0001"); // if TXIE is set, errant call occurred
__asm("\t JZ\t Start_Normal"); // if not start main program
__asm("\t RETI"); // else return from interrupt call
__asm("Start_Normal");
/*---------------------------------------------------------------------- */
/* Initialize stack pointer. Stack grows toward lower memory. */
/*----------------------------------------------------------------------*/
```

USCI30 *USCI Module*

Function I2C mode master receiver / slave receiver

Description When the USCI I2C module is configured as a receiver (master or slave), it performs a double-buffered receive operation. In a transaction of two bytes, once the first byte is moved from the receive shift register to the receive buffer the byte is acknowledged and the state machine allows the reception of the next byte.

If the receive buffer has not been cleared of its contents by reading the UCBxRXBUF register while the 7th bit of the following data byte is being received, an error condition may occur on the I2C bus. Depending on the USCI configuration the following may occur:

1) If the USCI is configured as an I2C master receiver, an unintentional repeated start

condition can be triggered or the master switches into an idle state (I2C communication aborted). The reception of the current data byte is not successful in this case.

2) If the USCI is configured as I2C slave receiver, the slave can switch to an idle state stalling I2C communication. The reception of the current data byte is not successful in this case. The USCI I2C state machine will notify the master of the aborted reception with a NACK.

Note that the error condition described above occurs only within a limited window of the 7th bit of the current byte being received. If the receive buffer is read outside of this window (before or after), then the error condition will not occur.

Workaround

a) The error condition can be avoided altogether by servicing the UCBxRXIFG in a timely manner. This can be done by (a) servicing the interrupt and ensuring UCBxRXBUF is read promptly or (b) Using the DMA to automatically read bytes from receive buffer upon UCBxRXIFG being set.

OR

b) In case the receive buffer cannot be read out in time, test the I2C clock line before the UCBxRXBUF is read out to ensure that the critical window has elapsed. This is done by checking if the clock line low status indicator bit UCSCLLOW is set for atleast three USCI bit clock cycles i.e. 3 X t(BitClock).

Note that the last byte of the transaction must be read directly from UCBxRXBUF. For all other bytes follow the workaround:

Code flow for workaround

(1) Enter RX ISR for reading receiving bytes

(2) Check if UCSCLLOW.UCBxSTAT == 1

(3) If no, repeat step 2 until set

(4) If yes, repeat step 2 for a time period > 3 x t (BitClock) where t (BitClock) = 1/ f (BitClock)

(5) If window of 3 x t(BitClock) cycles has elapsed, it is safe to read UCBxRXBUF

USCI35 *USCI Module*

Function

Violation of setup and hold times for (repeated) start in I2C master mode

Description

In I2C master mode, the setup and hold times for a (repeated) START, $t_{SU,STA}$ and $t_{HD,STA}$ respectively, can be violated if SCL clock frequency is greater than 50kHz in standard mode (100kbps). As a result, a slave can receive incorrect data or the I2C bus can be stalled due to clock stretching by the slave.

Workaround

If using repeated start, ensure SCL clock frequencies is < 50kHz in I2C standard mode (100 kbps).

XOSC5 *XOSC Module*

Function

LF crystal failures may not be properly detected by the oscillator fault circuitry

Description

The oscillator fault error detection of the LFXT1 oscillator in low frequency mode (XTS = 0) may not work reliably causing a failing crystal to go undetected by the CPU, i.e. OFIFG will not be set.

Workaround

None

XOSC8 *XOSC Module*

Function ACLK failure when crystal ESR is below 40 kOhm.

Description When ACLK is sourced by a low frequency crystal with an ESR below 40 kOhm, the duty cycle of ACLK may fall below the specification; the OFIFG may become set or in some instances, ACLK may stop completely.

Workaround Please refer to "XOSC8 Guidance" found at SLAA423 for information regarding working with this erratum.

4 Document Revision History

Changes from family erratasheet to device specific erratasheet.

1. Errata FLASH36 was added
2. Errata SYS15 was added

Changes from device specific erratasheet to document Revision A.

1. Errata EEM20 was added to the errata documentation.

Changes from document Revision A to Revision B.

1. BCL12 Workaround was updated.

Changes from document Revision B to Revision C.

1. Errata TA21 was added to the errata documentation.

Changes from document Revision C to Revision D.

1. Errata USCI35 was added to the errata documentation.

Changes from document Revision D to Revision E.

1. Errata BCL16 was added to the errata documentation.
2. Silicon Revision C was added to the errata documentation.

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Only those TI components which TI has specifically designated as military grade or “enhanced plastic” are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have ***not*** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

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